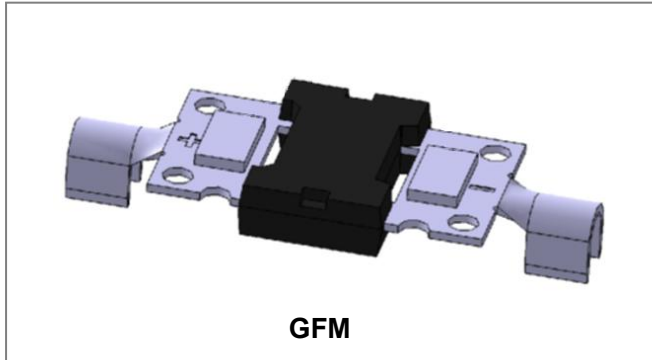


GF3045TS Power Schottky Module Bypass Diode



Features

- Low thermal resistance
- Lower forward voltage drop, low power loss
- Isolate Package design, ideal for heat dispersion
- High forward current capability
- Trench MOS Schottky technology
- Excellent anti-humidity
- Low profile package
- High forward surge capability
- All SMC parts are traceable to the wafer lot
- Additional electrical and life testing can be performed upon request

Mechanical Data

- Case: GFM
- Terminals: Copper
- High temperature soldering guaranteed
- Heated-tool welding 260°C, 10seconds
- Marking Code: GF3045TS

Maximum Ratings (limiting values, at 25 °C unless otherwise specified)

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	-	45	V
Average Rectified Forward Current	$I_F (AV)$	$T_C = 125^\circ\text{C}$, In DC	30	A
Peak One Cycle Non-Repetitive Surge Current	I_{FSM}	8.3 ms, half Sine pulse	350	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	V_{F1}	@ 30A, Pulse, $T_J = 25^\circ\text{C}$	0.49	0.55	V
Reverse Current*	I_{R1}	@ $V_R = \text{rated } V_R$, $T_J = 25^\circ\text{C}$	0.02	0.2	mA
	I_{R2}	@ $V_R = \text{rated } V_R$, $T_J = 100^\circ\text{C}$	-	20	mA
Junction Capacitance	C_T	@ $V_R = 5\text{V}$, $T_C = 25^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	3680	-	pF

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	IN DC Forward Mode, without reverse bias, $t \leq 1$ h	-55 to +200	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-	-55 to +150	$^{\circ}\text{C}$
Typical Thermal Resistance Junction to Case	$R_{\theta\text{JC}}$	-	1.5	$^{\circ}\text{C/W}$

Ratings and Characteristics Curves

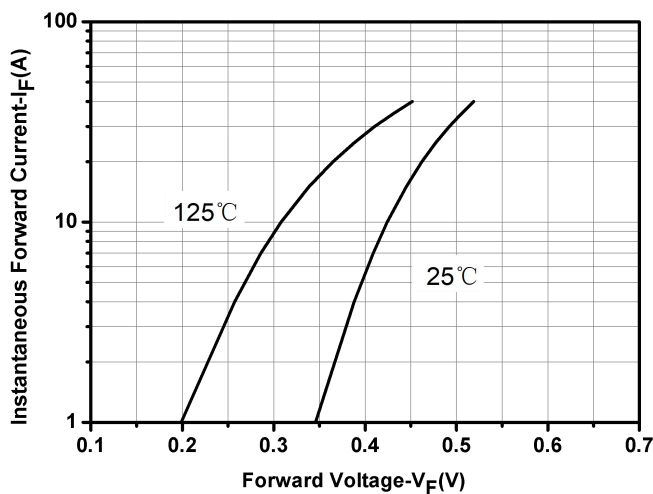


Fig.1-Typical Forward Voltage Characteristics

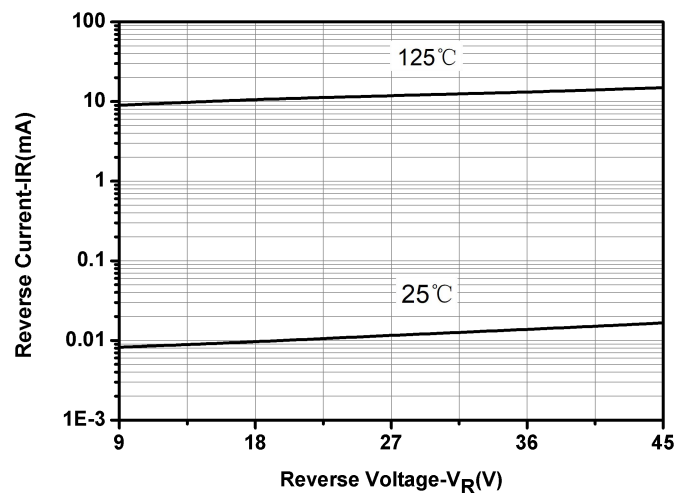


Fig.2-Typical Reverse Characteristics

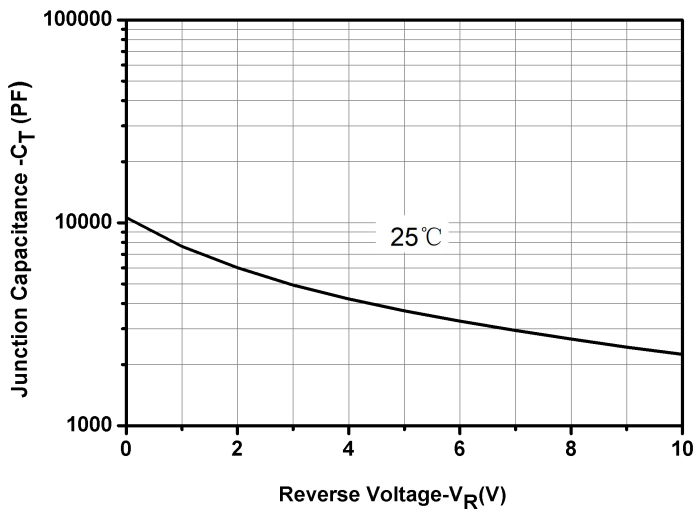
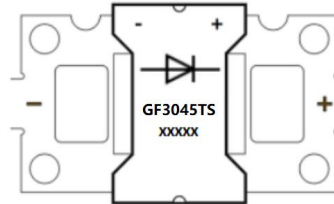


Fig.3-Capacitance vs. Reverse Voltage

Ordering Information

Device	Package	Shipping
GF3045TS	GFM	30pcs / Tube

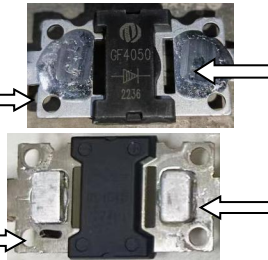
Marking Diagram



Where XXXXX is YYWWL

GF3045TS = Marking Code
YY = Year
WW = Week
L = Lot Number

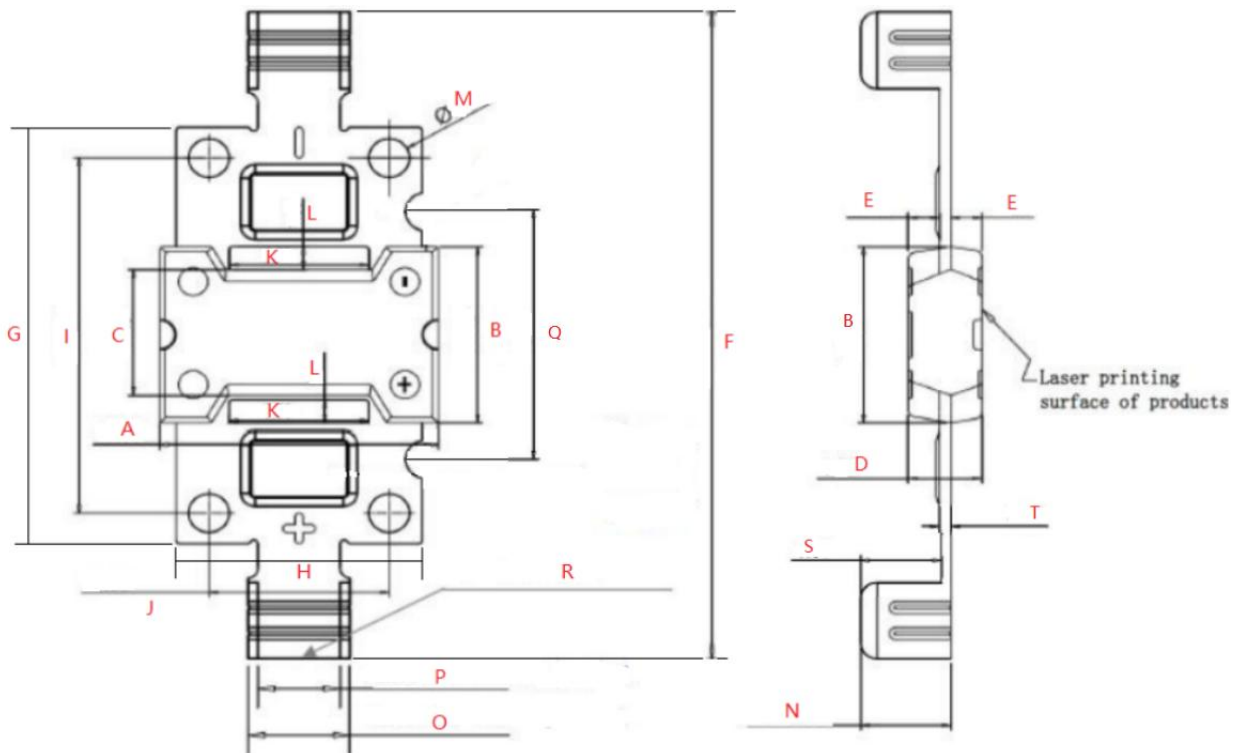
Order P/N	Terminals	Additional
GF3045TS-S1	Tin Plated	None
GF3045TS-S2	Tin Plated	Solder Paste
GF3045TS-S3	Tin Plated	Solder Block
GF3045TS-N1	Nickel Plated	None
GF3045TS-N2	Nickel Plated	Solder Paste
GF3045TS-N3	Nickel Plated	Solder Block



Solder Paste

Solder Block

Mechanical Dimensions GFM (Millimeters)



Symbol	Dimensions in millimeters		
	Min.	Typical	Max
A	16.90	17.00	17.10
B	11.38	11.48	11.58
C	8.15	8.20	8.25
D	4.40	4.50	4.60
E	1.85	1.90	1.95
F	41.90	42.00	42.10
G	26.90	27.00	27.10
H	14.90	15.00	15.60
I	22.90	23.00	23.10
J	10.90	11.00	11.10
K	-	8.50	-
L	-	1.50	-
M	-	∅ 2.50	2.55
N	5.35	5.50	5.65
O	6.20	6.30	6.40
P	4.90	5.00	5.10
Q	15.95	16.00	16.05
R	2.80	2.90	3.00
S	4.75	4.80	4.85
T	0.67	0.70	0.73

Dimension H includes Burrs/cutting residuals.

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